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EPOXY DC-203, DC-203-1

Medium to high flow, highly cross-linked epoxy system.

Designed for sealing PCB components.

Holds up well to industrial solvent exposure and soldering temperatures up to 325°C.

Capable of UL94HB flammability rating.

RECOMMENDED CURE SCHEDULES FOR DC-203, DC-203-1

212°F (100°C) for 4 hours minimum

250°F (125°C) for 1 hour minimum

300°F (150°C) for 30 minutes minimum

350°F (175°C) for 15 minutes minimum

SPECIFICATIONS

CURE METHOD: We recommend the use of forced convection ovens for curing our epoxy systems. When using static air ovens, recommended cure times should be doubled. Recommended cure schedules are for epoxy only. Place thermocouples throughout the oven to determine the influence of component mass on oven temperature and recovery time. Please refer to "Uni-form Epoxies Recommendations" bulletin for additional curing instructions.

ASTM D257	Volume Resistivity (ohms/inch)	$1.0 \times 10^{11} - 10^{13}$
ASTM D570	Water Absorption (weight %)	0.50 max.
ASTM D696	Coefficient Thermal Expansion (in/in °C)	$5.0 - 6.0 \times 10^{-5}$
ASTM D955	Shrinkage from Mold (inches/inch)	$0.2 - 0.4 \times 10^{-2}$
ASTM D2240	Durometer Hardness (Shore D)	80-84
ASTM D149	Dielectric Strength (60 Hz, volts/mil)	800 min.
DSC METHOD	Thermal Conductivity (cal·cm/sec·cm ² ·°C)	$4.5 - 5.5 \times 10^{-4}$

PLEASE NOTE: This information is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished up the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.